



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-03-27
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TXN825RG	7AVT*258TNL1	A	3068	2018-03-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10,15.5,4.5	3	Through-hole	
Comment				

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-l	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	4.89	Die - Leadframe	2574
Lead	61.85	Soft solder - Solder paste	32552
Lead-Borate Glass	2.39	Die	1260

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7AVT*258TNL1									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	42.817	mg	supplier	die	Silicon (Si)	7440-21-3		5.007	mg	116940	2635				
				supplier	metallization	Gold (Au)	7440-57-5		0.042	mg	981	23				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.219	mg	5115	115				
				JIG - R	Passivation	Lead (Pb)	7439-92-1	7c-I-Electrical and e	34.782	mg	812341	18306				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.062	mg	1448	33				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.014	mg	327	7				
Leadframe	M-004 Copper and its alloys	1594.514	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.297	mg	6936	156				
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4		2.394	mg	55912	1260				
				supplier	alloy	Copper (Cu)	7440-50-8		1590.477	mg	997468	837093				
Soft solder	Solder	11.461	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.733	mg	460	386				
				supplier	metallization	Nickel (Ni)	7440-02-0		3.304	mg	2072	1739				
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	10.601	mg	924963	5579				
Bonding wires	M-004 Copper and its alloys	31.625	mg	supplier	solder	Tin (Sn)	7440-31-5		0.287	mg	25041	151				
				supplier	solder	Silver (Ag)	7440-22-4		0.573	mg	49996	302				
				supplier	wire	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645				
				Encapsulation	M-011 Other inorganic materials	107.513	mg	supplier	mold compound	Silica, vitreous	60676-86-0		81.710	mg	760001	43005
								supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		10.966	mg	101997	5772
								supplier	mold compound	Phenol resin	9003-35-4		6.451	mg	60002	3395
solder paste	Solder	16.556	mg	supplier	mold compound	Others	Proprietary		5.376	mg	50003	2829				
				supplier	mold compound	Metal hydroxide	Proprietary		2.150	mg	19998	1132				
				supplier	mold compound	Carbon black	1333-86-4		0.860	mg	7999	453				
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	14.072	mg	849964	7406				
				supplier	solder	Antimony (Sb)	7440-36-0		1.656	mg	100024	872				
				supplier	solder	Tin (Sn)	7440-31-5		0.828	mg	50012	436				
connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323				
Ceramic	M-010 Ceramics / glass	89.200	mg	supplier	ceramic	Alumina	1344-28-1		79.745	mg	894002	41971				
				supplier	ceramic	Molybdenum oxide	1313-27-5		4.460	mg	50000	2347				
				supplier	ceramic	Manganese (Mn)	7439-96-5		3.479	mg	39002	1831				
				supplier	ceramic	Nickel (Ni)	7440-02-0		1.070	mg	11996	563				
				supplier	ceramic	Titanium (Ti)	1344-28-1		0.366	mg	4103	193				
				supplier	ceramic	Phosphorus (P)	12185-10-3		0.080	mg	897	42				